

IN THE SPECIFICATION:

Pages 3 and 4, amend the paragraph starting on page 3 at line 17 and ending on page 4 at line 1 as follows:

This object is achieved using a chip carrier with for forming a chip module with a substrate and connection leads arranged on the substrate. The connection leads are designed like stripes and extend parallel over the substrate. In the chip carrier according to the invention, the connection leads consist of electrically conductive connection strands placed on the substrate, and the substrate is formed by a carrier film.

Page 5, amend the paragraph starting at line 12 and ending at line 14 as follows:

If the connection strands of the chip carrier ~~are~~ are connected with the terminals of the coil unit, the chip carrier can serve as the basic unit for manufacturing a transponder, wherein the basic unit need only be enhanced by contact with a chip.

Page 6, amend the paragraph starting at line 13 and ending at line 17 as follows:

As already emphasized at the outset while describing the structure of the chip module according to the invention, the manufacturing process is characterized by the lowest possible number of steps, due to the fact that the substrate provided with connection leads is realized via a simple combination of connection strands with a carrier film, and and the type of contacting according to the invention enables a simple flip-chip contacting.

Page 7, amend the paragraph starting at line 1 and ending at line 4 as follows:

One particularly economic variant of the method according to the invention can be implemented if the connection strands are continuously applied to the carrier film, so that the connection strands and the carrier film are provided as continuous strands, and moved continuously toward each other in a contact area with the generation of an adhesion.

Page 7, amend the paragraph starting at line 12 and ending at line 13 as follows:

Therefore, this method variant enables the manufacture of an especially flat or thin chip module.